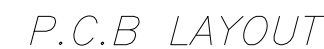
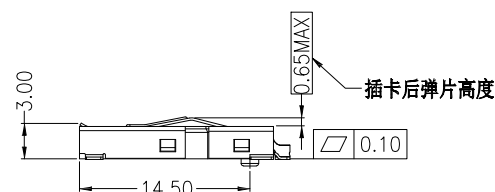
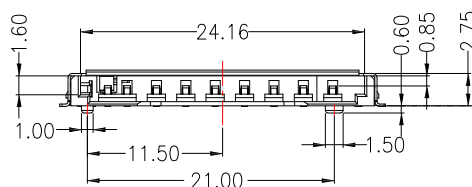
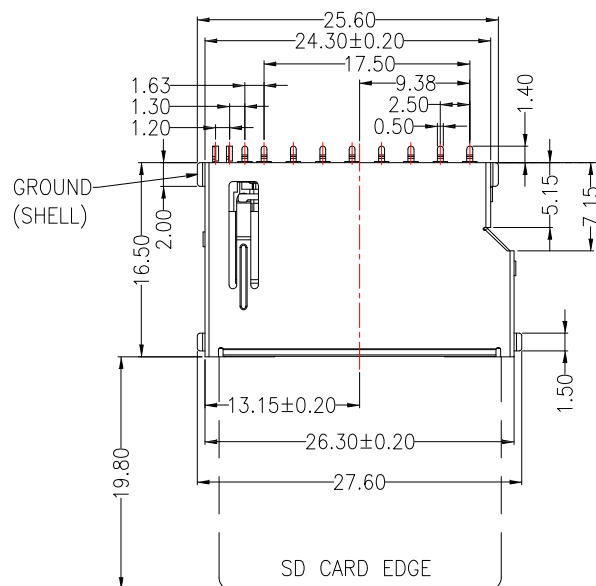


| PIN NO. | NAME    | DESCRIPTION          |
|---------|---------|----------------------|
| 1#      | CD/DAT3 | CARD DETECT/DATA I/O |
| 2#      | CMD     | COMMAND              |
| 3#      | VSS1    | GROUND               |
| 4#      | VDD     | POWER                |
| 5#      | CLK     | CLOCK                |
| 6#      | VSS2    | GROUND               |
| 7#      | DAT0    | DATA I/O             |
| 8#      | DAT1    | DATA I/O             |
| 9#      | DAT2    | DATA I/O             |
| 10#     | CD      |                      |
| 11#     | WP      |                      |



- 1.MATERIAL:
  - 1.1 HOUSING: LCP
  - 1.2 CONTACT: PHOSPHOR BRONZE
  - 1.3 COVER: BRASS
- 2.PLATING:
  - 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
TIN PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
  - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.ELCTRICAL & MECHANICAL PARAMETER
  - 3.1 CURRENT RATING: 0.5A
  - 3.2 CONTACT RESISTANCE: 100m $\Omega$  MAX
  - 3.3 INSULATION RESISTANCE: 1000M $\Omega$  MIN
  - 3.4 WITHSTANDING STRENGTH: 500V AC
  - 3.5 INSERTION FORCE: 10N MAX
  - 3.6 SEPARATION FORCE: 2N MIN
  - 3.7 OPERATING TEMPERATURE: -25°C ~ 90°C